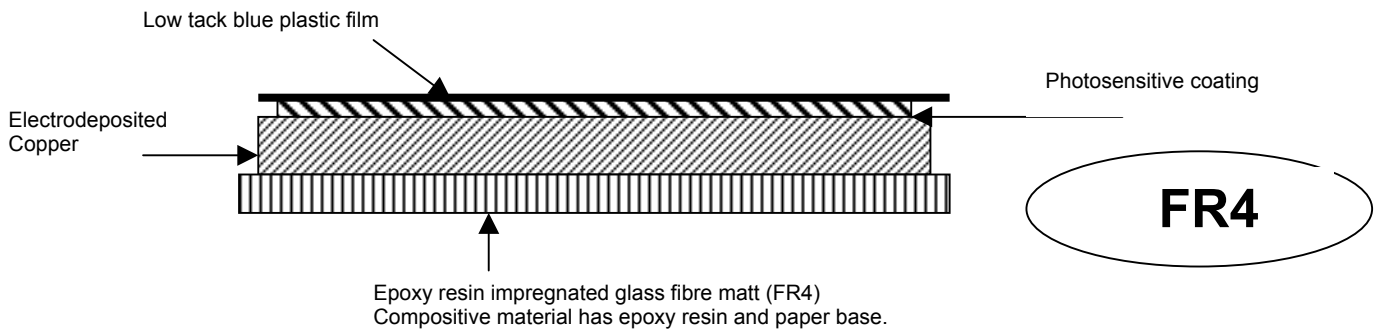


fr4 AND COMPOSITE PRE-SENSITISED PCB LAMINATES

High quality dip coated positive working photoresist. This high resolution photoresist contains a dye which gives a good contrast against the copper, allowing boards to be easily inspected at the developing stage. Panels are protected by a specially designed light-proof blue film which allows them to be guillotined without the risk of fracturing the Photoresist.



	FR4 Laminate
Thickness	1.6mm
Copper foil	35 microns
Dissipation factor	35
Dielectric Constant	5.4
Solderbath resistance (260°)	20 secs.
Resist thickness	5 microns
Spectral response	350 – 450 nm
U.V. light energy required approx.	50ml / cm
Shelf life	1 year at 15 – 20°C
Developer	3204996
Etchant	Ferric Chloride Pellets or liquid and Fine Etch Crystals.

U.V. EXPOSURE

Use a good quality artwork and purpose made U.V. exposure unit. The exact exposure time will vary, depending on the quality of the artwork used and the size of the U.V. unit.

As a guide: Exposure times between 90 seconds and 120 seconds are normally sufficient.

DEVELOPING THE RESIST

Use 3204996 Developer concentrate. Mix as instructed and use between 18°C – 24°C, preferably in a heated Processing Tank (157363). Developing time will depend on artwork, exposure and developer temperature, 30 seconds to 180 seconds is typical.

Ready to use 141-310 Developer can also be used with this board, but the above mentioned 3204996 is recommended as the preferred developer.

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